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Attorney

44,248  
Reg. No.

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant : Nishimura Tetsuro  
Serial No. : 09/450,632  
Filed : November 24, 1999  
Title : LEAD-FREE SOLDER-ALLOY  
Docket : 550718-070  
Art Unit : 1742

BOX NON-FEE AMENDMENT  
Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

**SECOND PRELIMINARY AMENDMENT**

Prior to examination, please amend the above-identified application as follow:

IN THE CLAIMS:

Please cancel claims 4, ~~5~~, and 6; and add the following new claims 7-15:

- B<sub>1</sub>** ~~4~~ 7. A lead-free solder alloy according to claim 1 wherein Ni is added to a ~~solder~~ base alloy of Sn-Cu.
- ~~5~~ 8. A lead-free solder alloy according to claim 2 wherein Ni is added to a ~~solder~~ base alloy of Sn-Cu.